

Majid Samavatian

List of Publications by Year in descending order

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papers

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687363

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197
citing authors

#	ARTICLE	IF	CITATIONS
1	Iterative Machine Learning-Aided Framework Bridges Between Fatigue and Creep Damages in Solder Interconnections. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 349-358.	2.5	17
2	Characterization of nanoscale structural heterogeneity in metallic glasses: A machine learning study. Journal of Non-Crystalline Solids, 2022, 578, 121344.	3.1	13
3	Thermomechanical Fatigue Damage Model of a Solder Joint in Electronic Devices: An Interval Arithmetic Based Approach. Journal of Electronic Materials, 2022, 51, 5376-5388.	2.2	7
4	Discovery of novel quaternary bulk metallic glasses using a developed correlation-based neural network approach. Computational Materials Science, 2021, 186, 110025.	3.0	34
5	Improving the reliability of ball grid arrays under random vibration by optimization of module design. Mechanics of Advanced Materials and Structures, 2020, 27, 1748-1755.	2.6	10
6	Inherent relation between atomic-level stresses and nanoscale heterogeneity in Zr-based bulk metallic glass under a rejuvenation process. Physica B: Condensed Matter, 2020, 595, 412390.	2.7	17
7	Correlation-driven machine learning for accelerated reliability assessment of solder joints in electronics. Scientific Reports, 2020, 10, 14821.	3.3	47
8	Effects of Creep Failure Mechanisms on Thermomechanical Reliability of Solder Joints in Power Semiconductors. IEEE Transactions on Power Electronics, 2020, 35, 8956-8964.	7.9	34
9	Combination of thermal cycling and vibration loading effects on the fatigue life of solder joints in a power module. Proceedings of the Institution of Mechanical Engineers, Part L: Journal of Materials: Design and Applications, 2019, 233, 1753-1763.	1.1	19
10	Correlation Between Plasticity and Atomic Structure Evolution of a Rejuvenated Bulk Metallic Glass. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2019, 50, 4743-4749.	2.2	25
11	Extra rejuvenation of Zr ₅₅ Cu ₃₀ Al ₁₀ Ni ₅ bulk metallic glass using elastostatic loading and cryothermal treatment interaction. Journal of Non-Crystalline Solids, 2019, 506, 39-45.	3.1	34
12	Effects of Nb minor addition on atomic structure and glass forming ability of Zr ₅₅ Cu ₃₀ Ni ₅ Al ₁₀ bulk metallic glass. Materials Research Express, 2019, 6, 065202.	1.6	20
13	Role of tensile elastostatic loading on atomic structure and mechanical properties of Zr ₅₅ Cu ₃₀ Ni ₅ Al ₁₀ bulk metallic glass. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2019, 753, 218-223.	5.6	37
14	Effect of solder layer thickness on thermo-mechanical reliability of a power electronic system. Journal of Materials Science: Materials in Electronics, 2018, 29, 15249-15258.	2.2	25
15	Transient liquid phase bonding of Al ₂₀₂₄ to Ti-6Al-4V alloy using Cu-Zn interlayer. Transactions of Nonferrous Metals Society of China, 2015, 25, 770-775.	4.2	26
16	An investigation on microstructure evolution and mechanical properties during liquid state diffusion bonding of Al ₂₀₂₄ to Ti-6Al-4V. Materials Characterization, 2014, 98, 113-118.	4.4	24